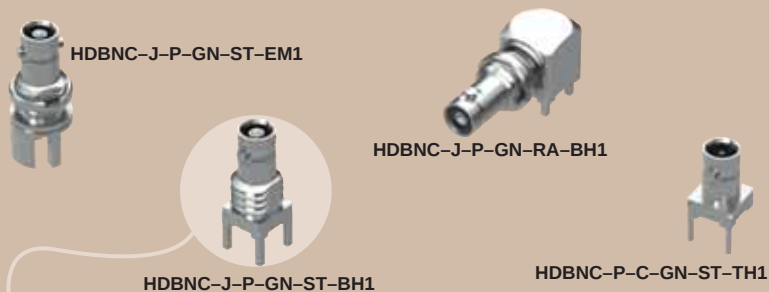




HDBNC SERIES



75Ω HIGH DENSITY BNC JACKS

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?HDBNC-TH, www.samtec.com?HDBNC-BH1 or www.samtec.com?HDBNC-EM

Shell Material:

Au plated Brass

Contact Material:

Copper Alloy

Insulator Material:

PTFE

Impedance:

75Ω ±2Ω

Frequency Range:

0-6 GHz

V.S.W.R:

1.45 max

(with optimized launch design)

Working Voltage:

330 Vrms max

Dielectric Withstanding:

1500 Vrms min

Contact Resistance:

Center Contact: 1.5mΩ max

Outer Contact: 0.4mΩ max

Operating Temperature:

-65°C to +125°C

RoHS Compliant:

Yes

Lead-Free Solderable:

Yes

Mates with:

RFB6T, RFB8T, RFA6T

4X THE PANEL DENSITY



Patented design
and bayonet latch

20% reduction in
weight of traditional
BNCs

Extended
performance
of 6 GHz for
high density

EXTRACTION TOOL

- Hand tool for quickly installing/uninstalling
- Contact Samtec.

HDBNC	GENDER	TYPE	PLATING	ORIENTATION	TERMINATION
	-J = Jack	-P = PCB Mount	-GN = 10μ" (0,25 μm) Gold contact, 100μ" (2,54 μm) Nickel shell	-ST = Straight -RA = Right Angle	-BH1 = Through-hole (1,60 mm) .062 Board -BH2 = Through-hole (2,36 mm) .093 Board (-RA only) -EM1 = Edge Mount (-ST only) -TH1 = Through-hole (-ST only)

Note: Compatible with Amphenol's HD-BNC™

* Designed to meet SMPTE 424M 3G SDI specification.

Due to technical progress, all designs, specifications and components are subject to change without notice.

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